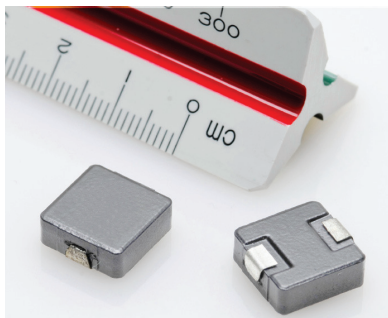


HCM1305

High current power inductors



Product features

- High current carrying capacity
- Low core losses
- Magnetically shielded, low EMI
- Frequency range up to 5 MHz
- Inductance range from 0.10 μ H to 33 μ H
- Current range from 5.2 A to 118 A
- 13.8 mm x 12.5 mm footprint surface mount package in a 5.0 mm height
- Iron powder core material

Applications

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Desktop and server VRMs and EVRDs
- Base station equipment
- Notebook and laptop regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

Environmental data

- Storage temperature range (component): -55 °C to +125 °C
- Operating temperature range: -55 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant



Product specifications

Part Number ⁶	OCL ¹ (μH) ± 20%	FLL ² Min. (μH)	I_{rms}^3 (A)	I_{sat}^4 (A)	DCR (mΩ) @ +20 °C ± nominal	DCR (mΩ) @ +20 °C maximum	K-factor ⁵
HCM1305-R10-R	0.10	0.064	55	118	0.52	0.59	848
HCM1305-R22-R	0.22	0.14	51	110	0.63	0.72	843
HCM1305-R33-R	0.33	0.21	42	80	0.80	0.92	506
HCM1305-R47-R	0.47	0.30	38	65	0.80	0.92	506
HCM1305-R56-R	0.56	0.36	36	55	1.15	1.33	500
HCM1305-R68-R	0.68	0.44	34	54	1.15	1.33	500
HCM1305-R82-R	0.82	0.52	31	53	1.40	1.61	358
HCM1305-1R0-R	1.00	0.64	29	50	2.10	2.42	275
HCM1305-1R5-R	1.50	0.96	23	48	2.75	3.16	225
HCM1305-1R8-R	1.80	1.15	21	40	4.00	4.60	216
HCM1305-2R2-R	2.20	1.41	20	32	4.60	5.29	191
HCM1305-3R3-R	3.30	2.11	15	32	7.70	9.20	170
HCM1305-4R7-R	4.70	3.01	12	27	11.0	12.7	161
HCM1305-5R6-R	5.60	3.58	11.5	22	12.0	13.8	142
HCM1305-6R8-R	6.80	4.35	11	21	13.0	15.0	129
HCM1305-7R8-R	7.80	4.99	10	18.5	16.8	19.4	117
HCM1305-8R2-R	8.20	5.25	9.5	18	17.5	20.1	117
HCM1305-100-R	10.0	6.40	9.0	16	19.0	21.9	90
HCM1305-150-R	15.0	9.60	7.7	13	29.0	33.4	74
HCM1305-220-R	22.0	14.1	6.2	10	45.0	51.8	63
HCM1305-330-R	33.0	21.1	5.2	8	74.5	85.5	48

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V_{rms}, 0.0 Adc, +25 °C.

2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25 V_{rms}, I_{sat}⁴ @ +25 °C.

3. I_{rms}³: DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.

4. I_{sat}⁴: Peak current for approximately 20% rolloff at +25 °C.

5. K-factor: Used to determine B_{p-p} for core loss (see graph). B_{p-p} = K * L * ΔI.
B_{p-p}: (Gauss), K: (K-factor from table), L: (Inductance in μH), ΔI (Peak to peak ripple current in amps).

6. Part Number Definition: HCM1305-yyy-R

- HCM1305 = Product code and size

yyy= Inductance value in μH, R = decimal point,

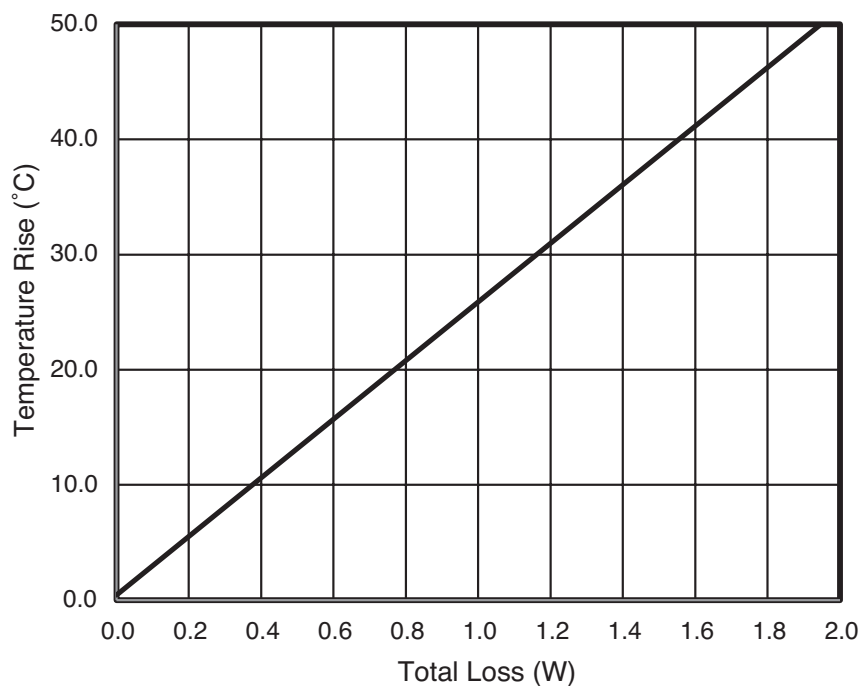
if no R is present then third character = number of zeros.

“-R” suffix = RoHS compliant

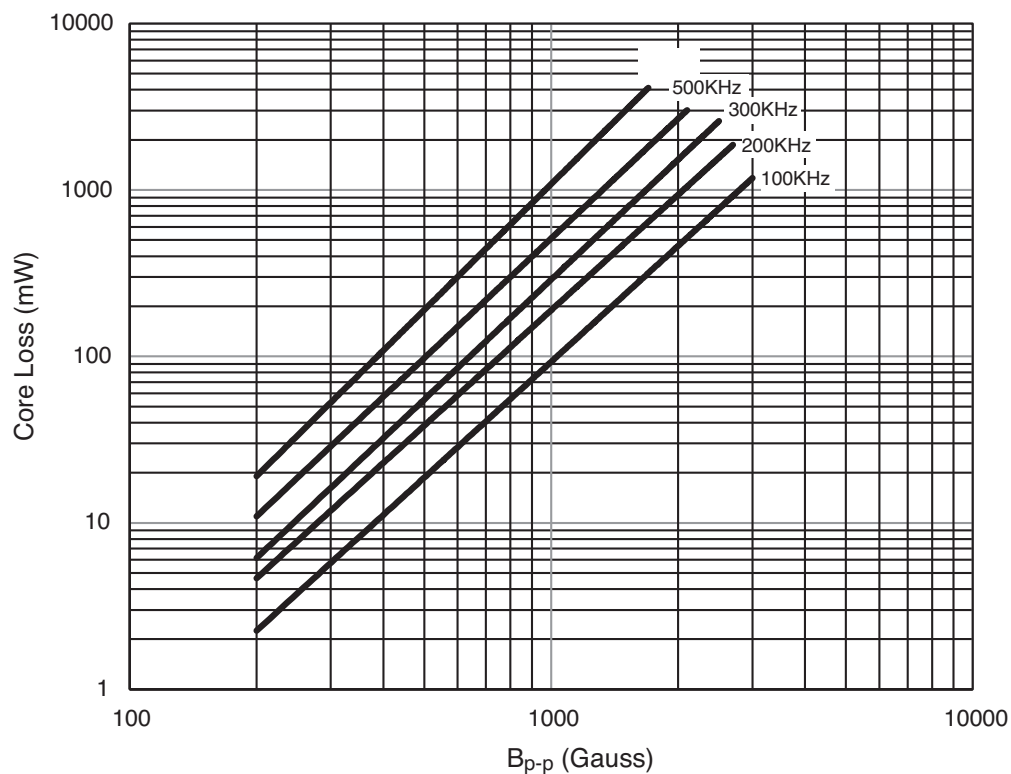
Do not route traces or vias underneath the inductor

Supplied in tape and reel packaging, 400 parts per 13" diameter reel.

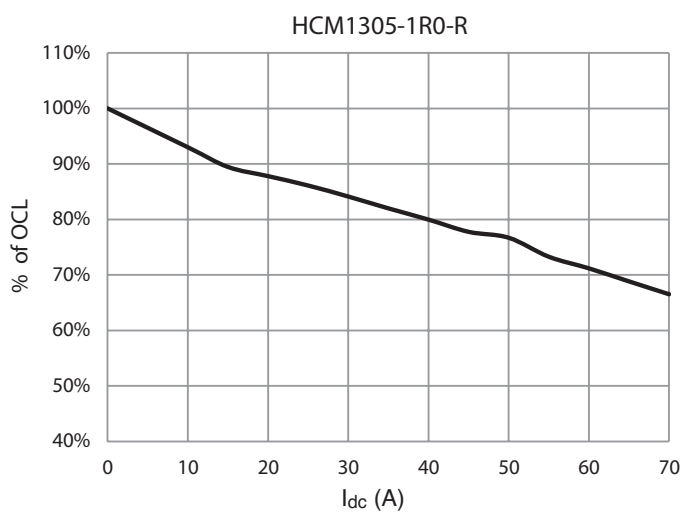
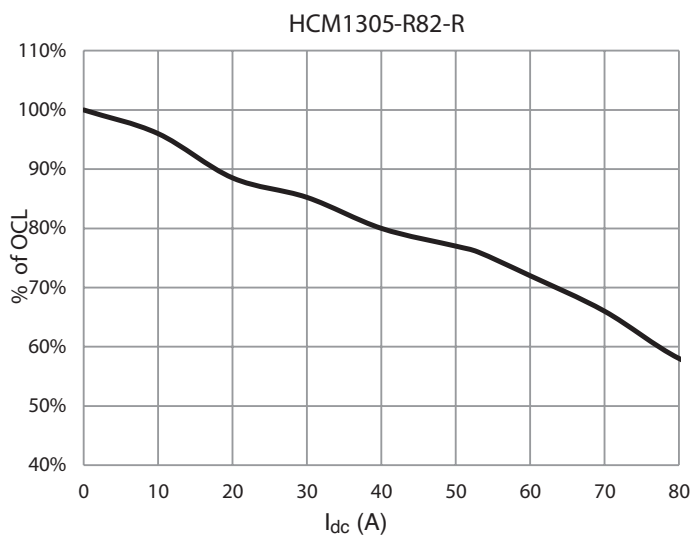
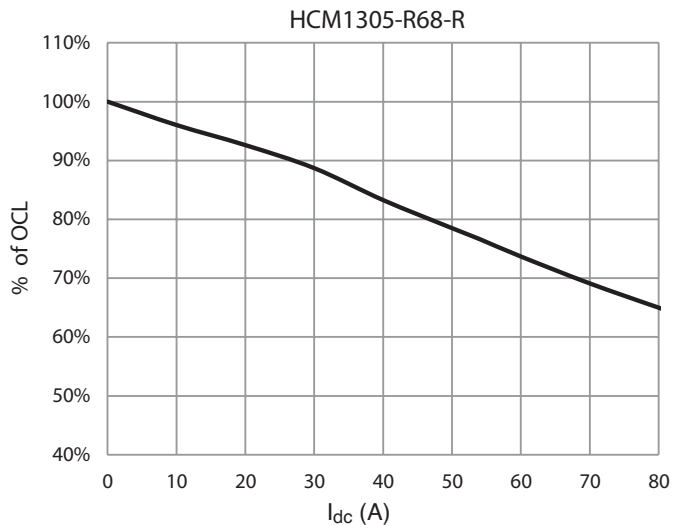
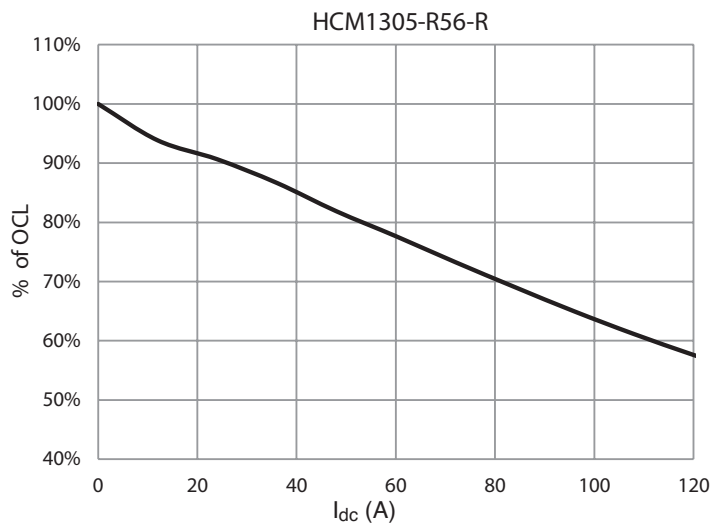
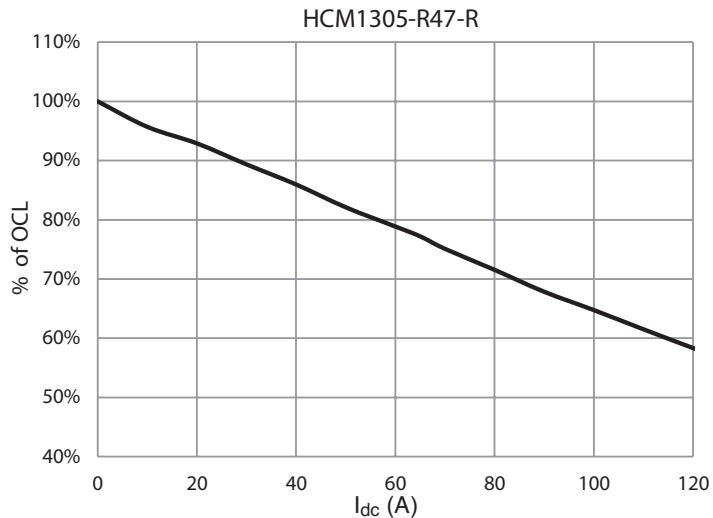
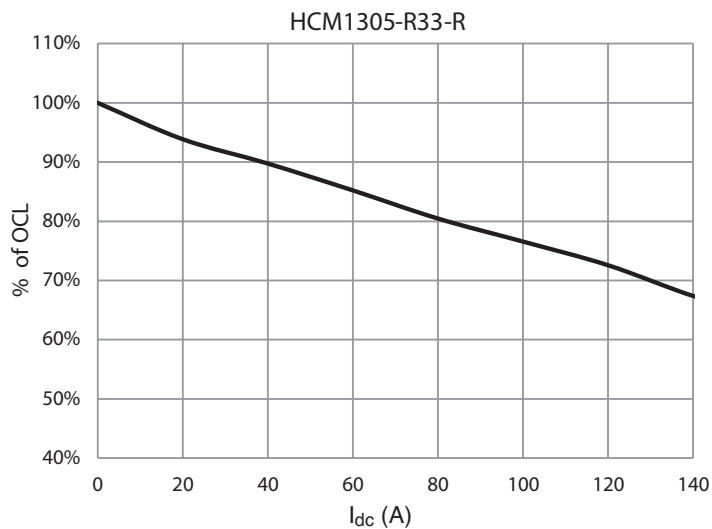
Temperature rise vs. total loss



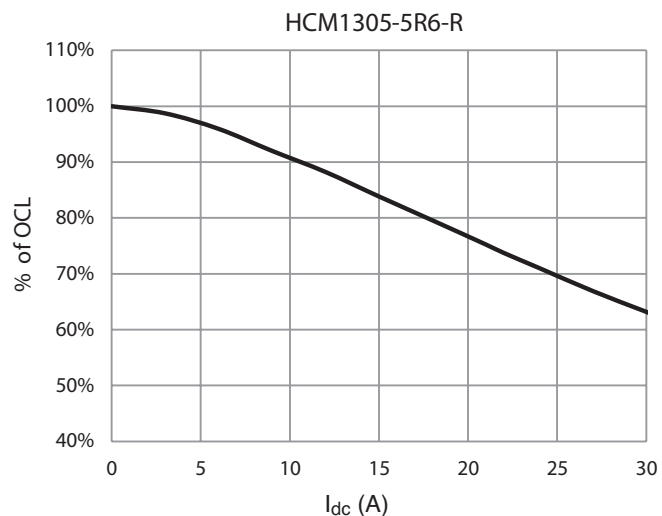
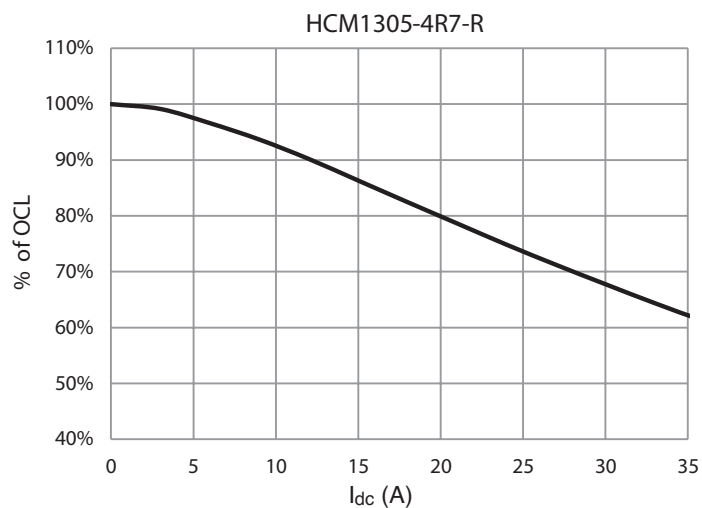
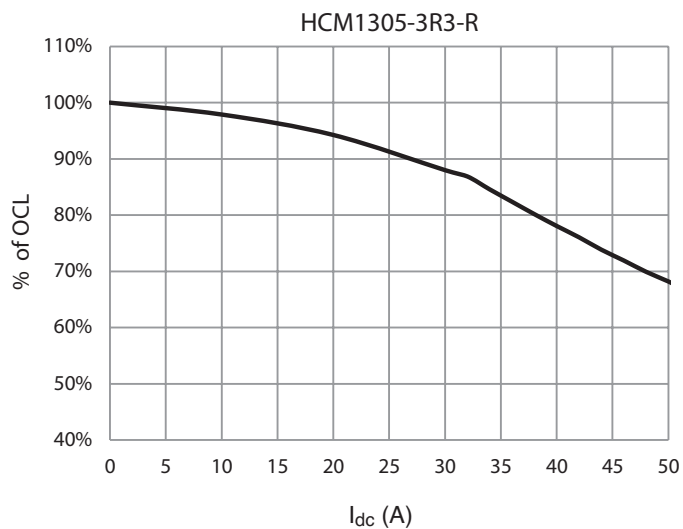
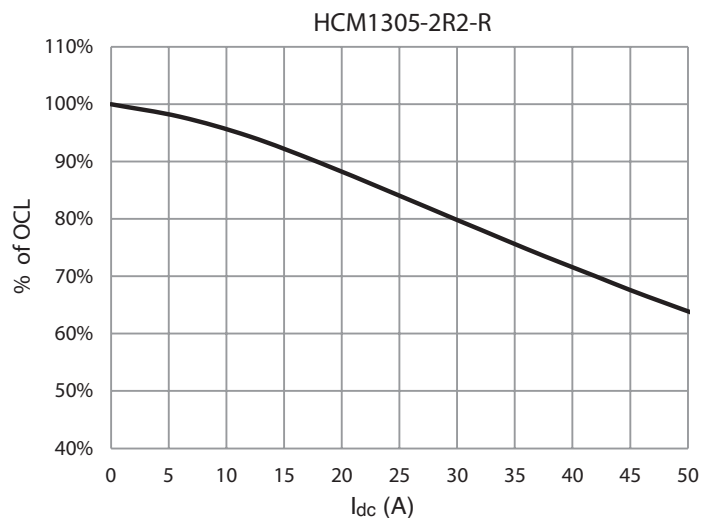
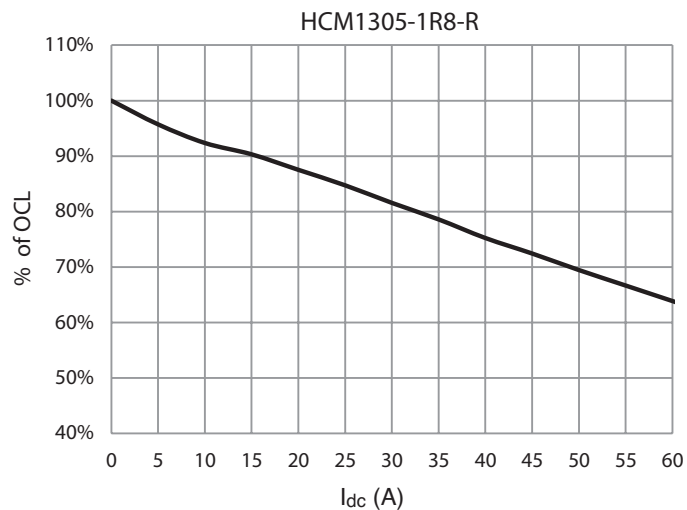
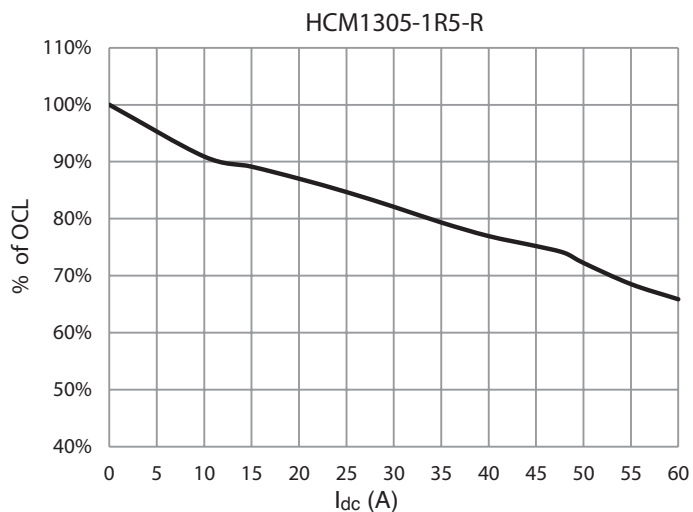
Core loss vs. B_{p-p}



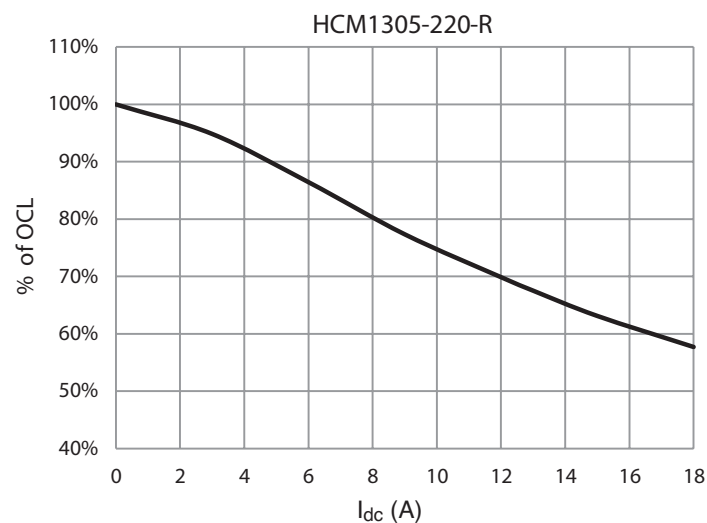
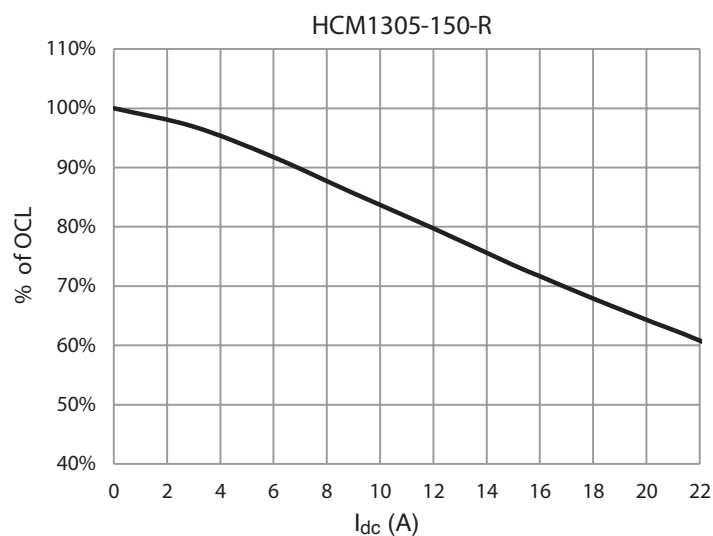
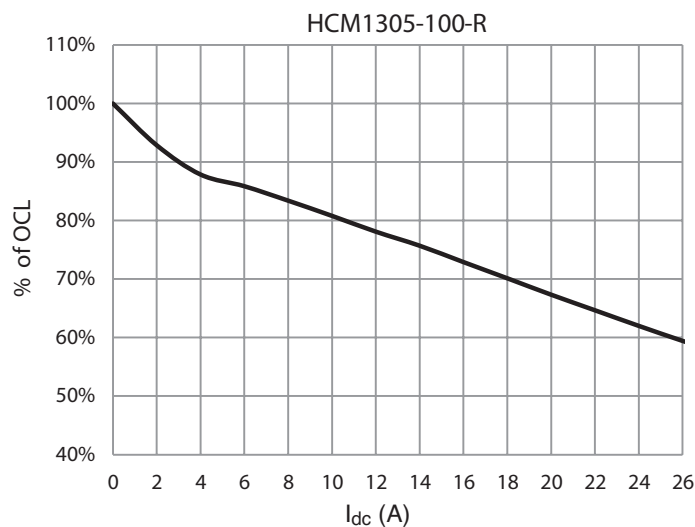
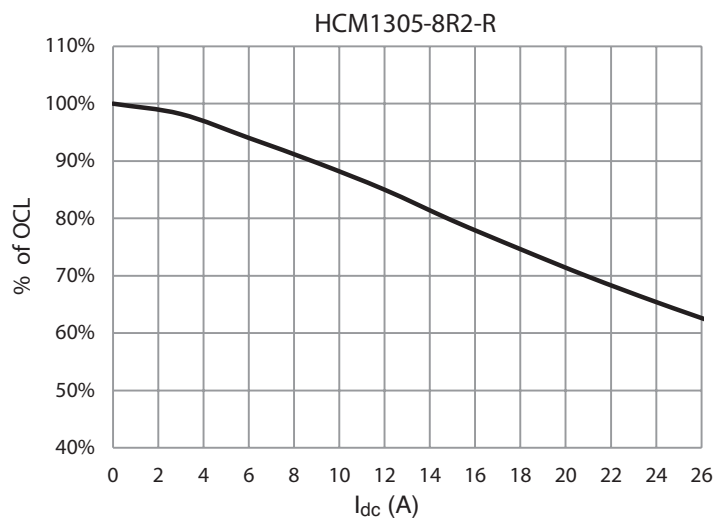
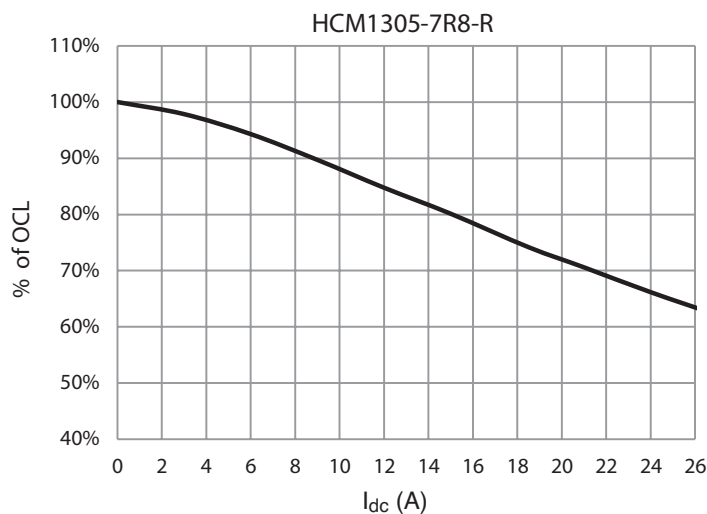
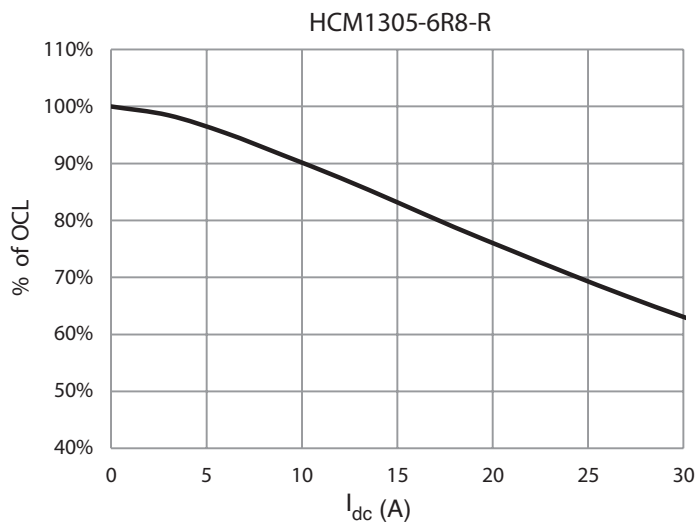
Inductance characteristics



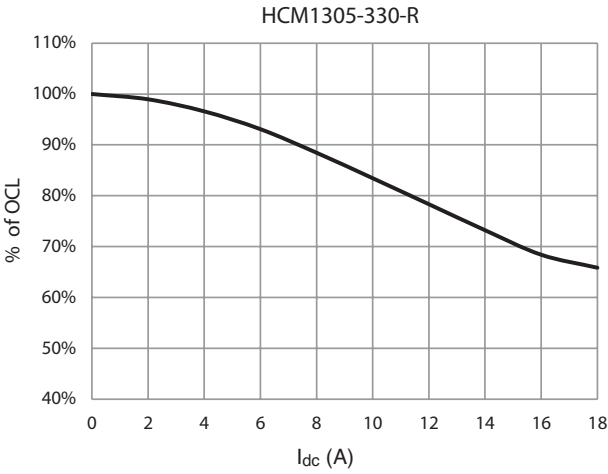
Inductance characteristics



Inductance characteristics



Inductance characteristics



Solder Reflow Profile

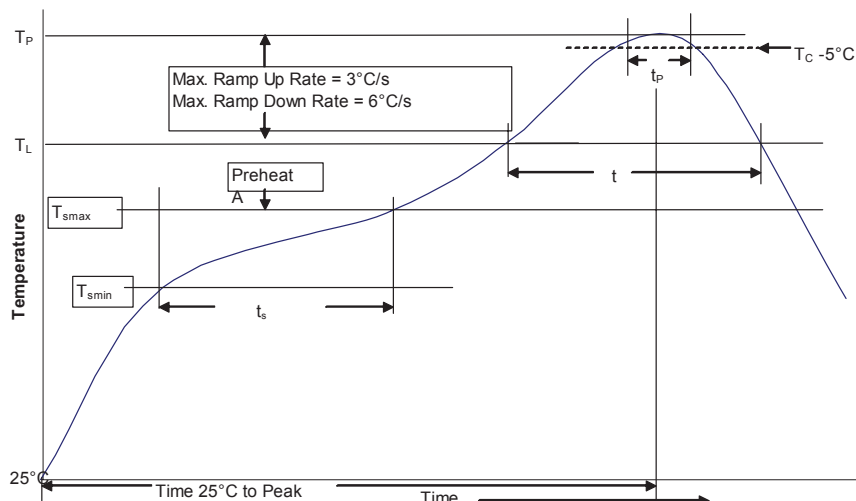


Table 1 - Standard SnPb Solder (T_p)

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥ 350
<2.5mm	235°C	220°C
$\geq 2.5mm$	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_p)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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